

- No Driving Source
- IO Pin - Output Port or Output Sheet
- IO Pin - Input Port or Input Sheet
- IO Pin - Power Pin
- IO Pin - Output Pin
- Power Pin - Output Port or Output Sheet
- Power Pin - Input Port or Input Sheet
- Power Pin - Output Pin
- Floating Input Pin
- Unconnected Wire
- Multiple Net Names
- Unconnected Sheet Entry

Change Log

REV A:

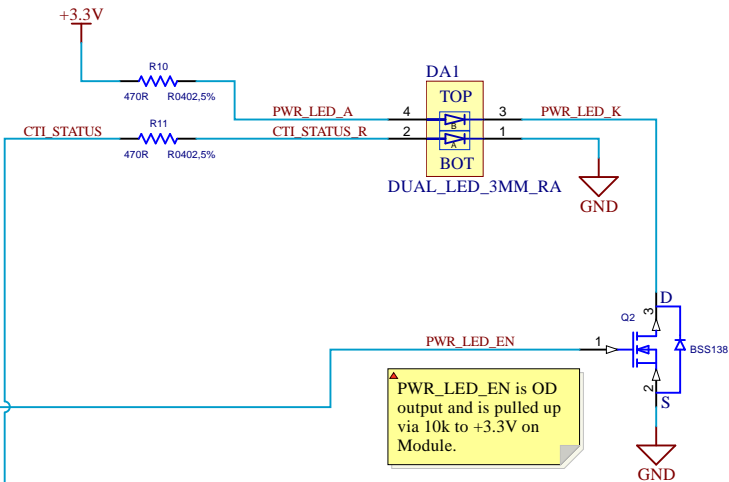
- Initial Revision MECH Sample Only

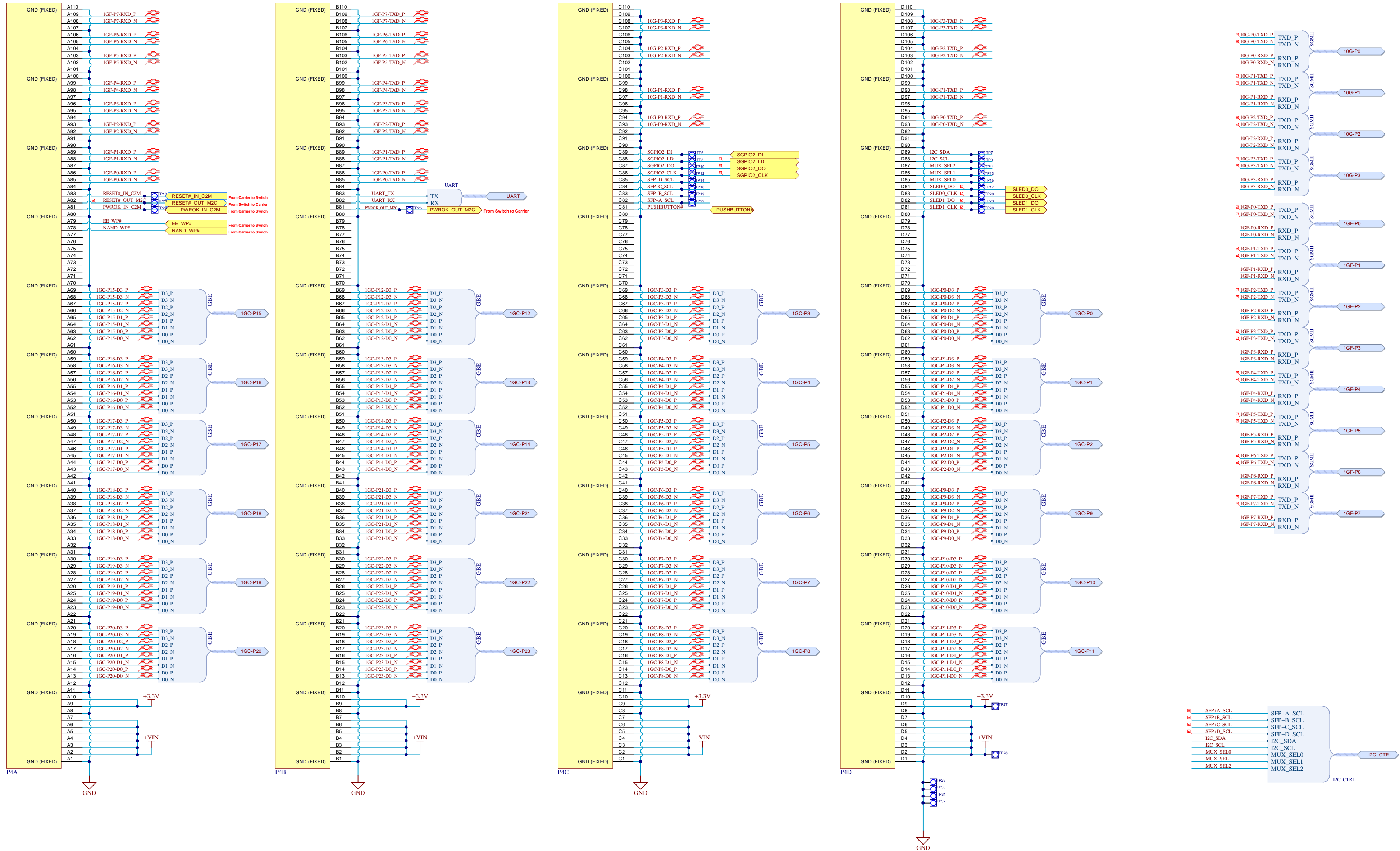
REV B:

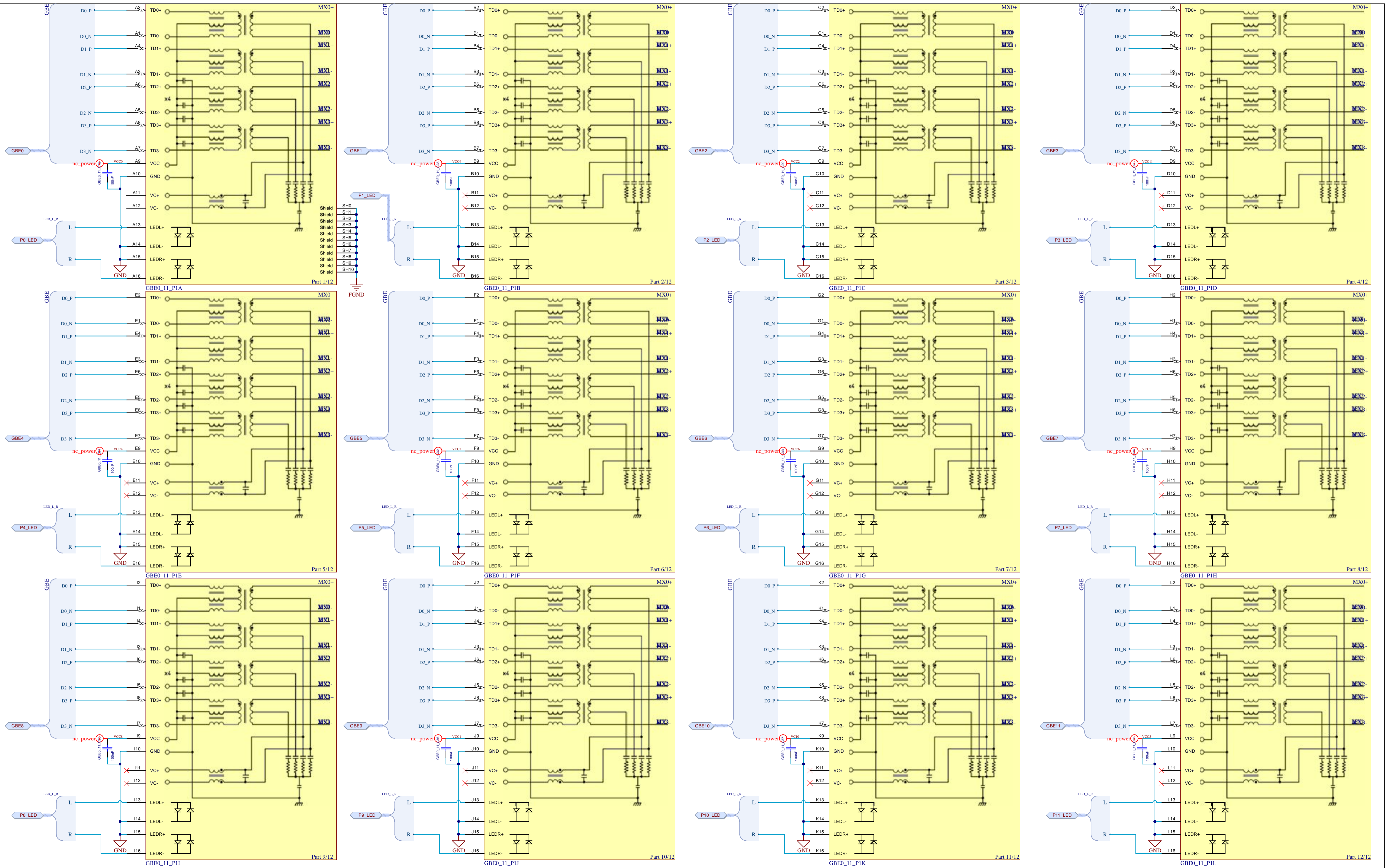
- Initial Prototype Revision

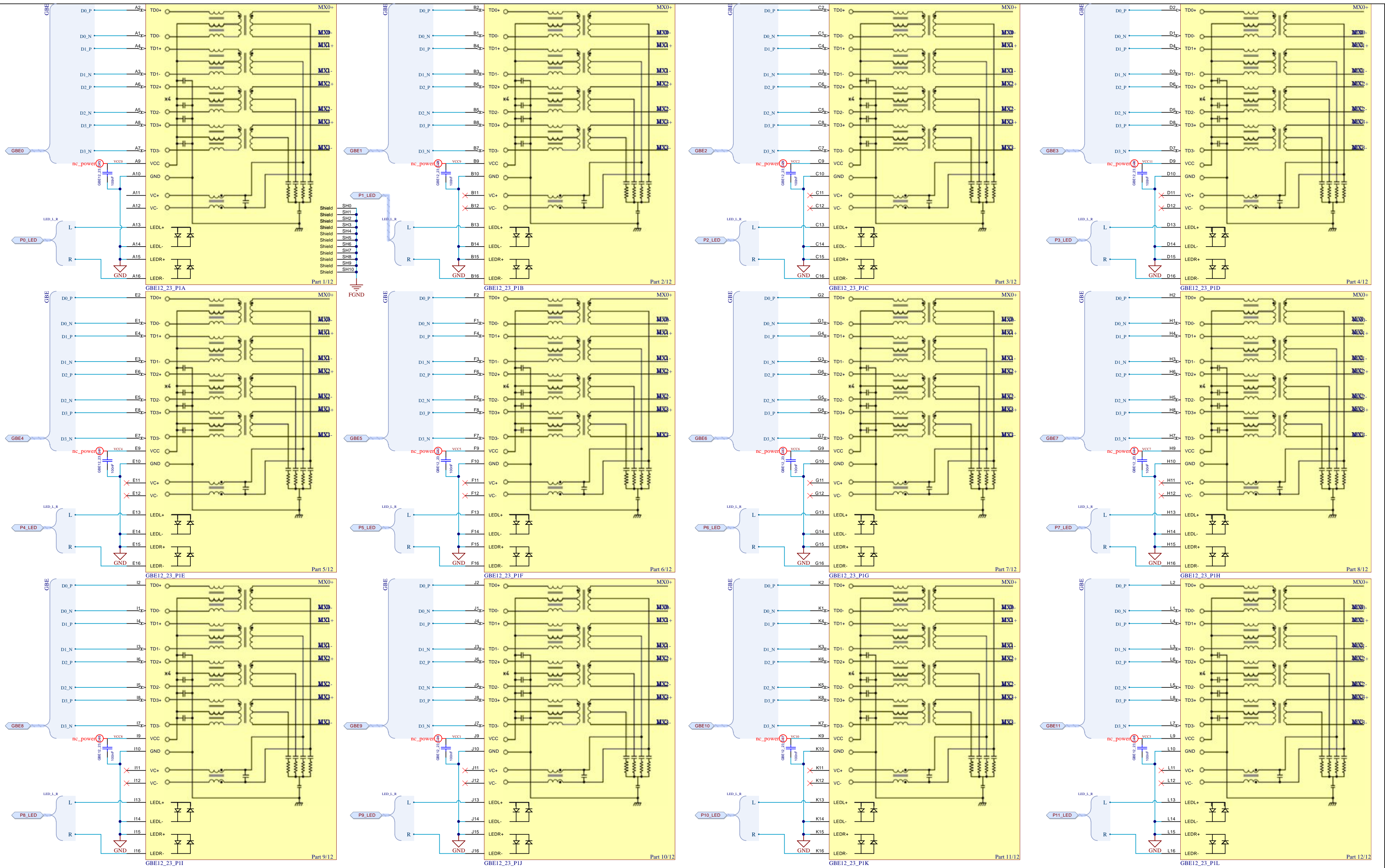
REV C:

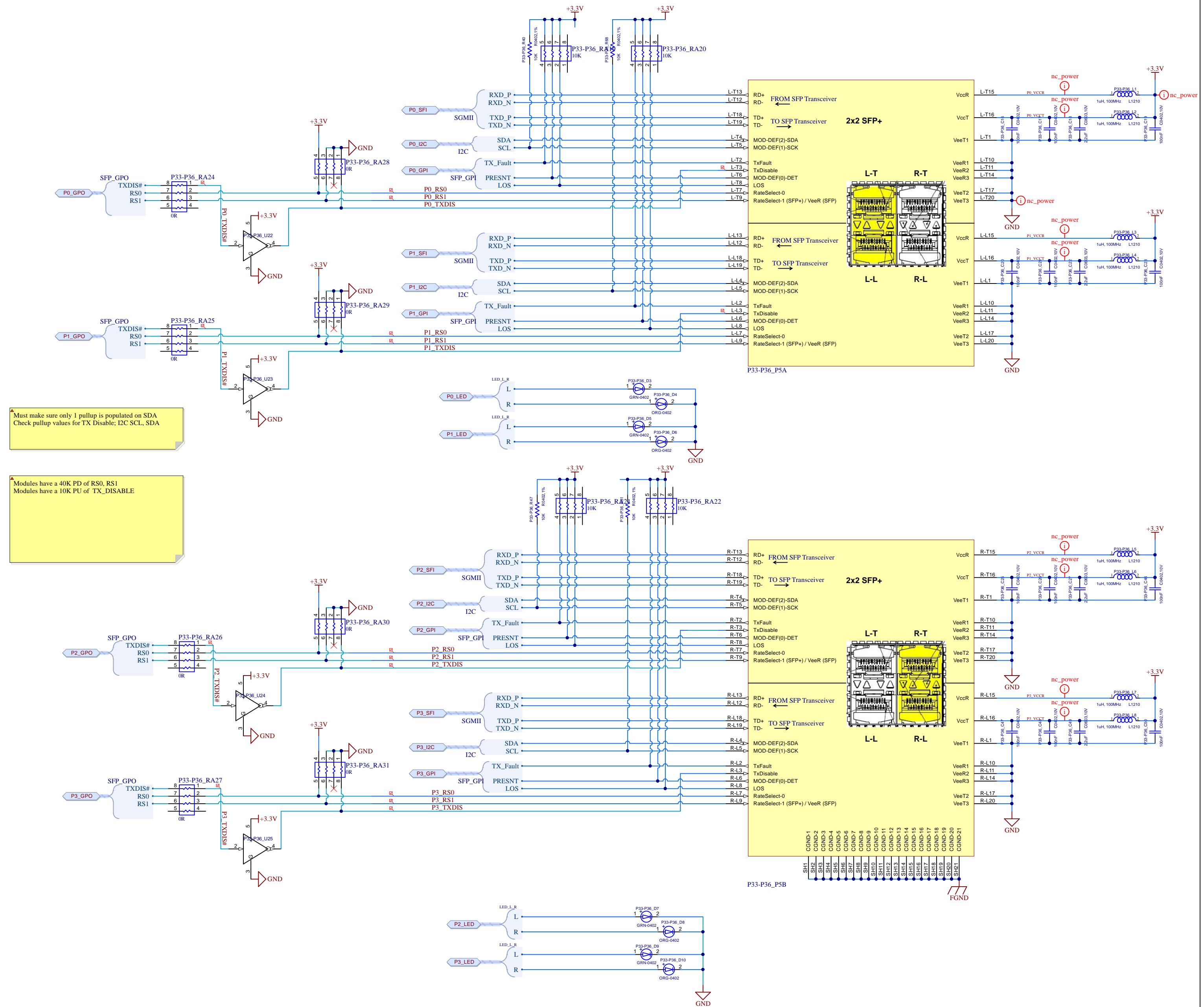
- Corrected mounting hole positions for XDG-2011 module
- Added EE and NAND Write Protect Control

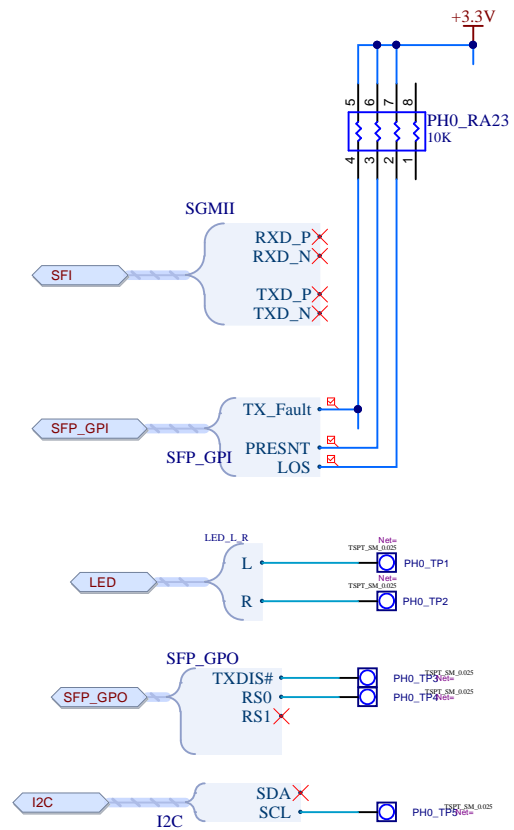


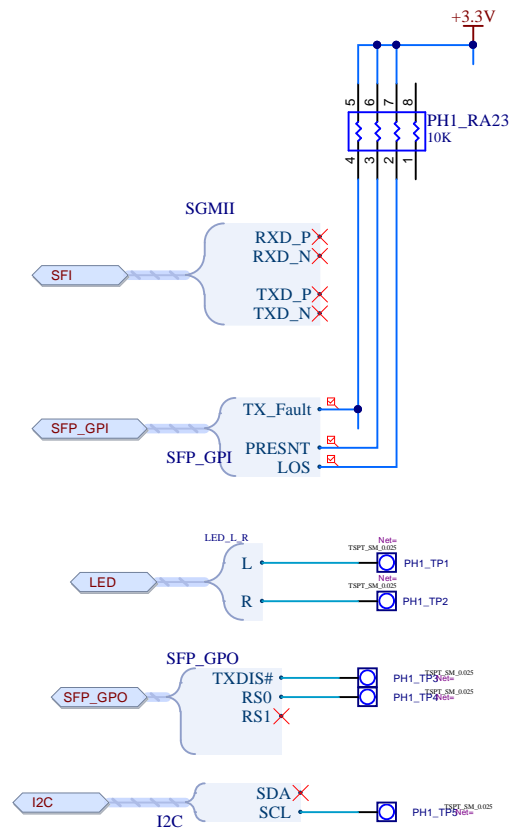


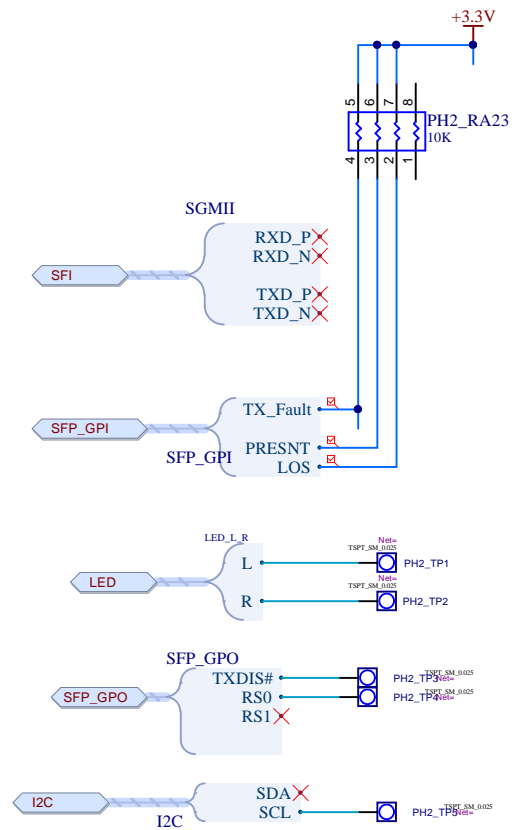


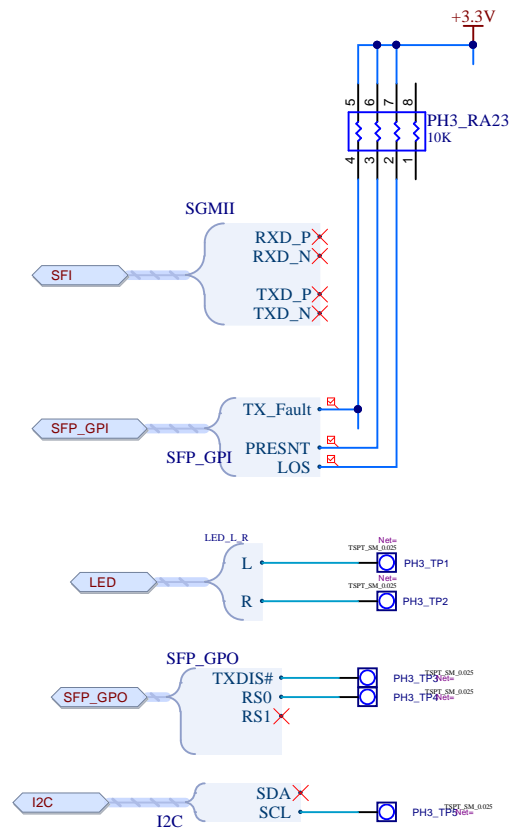


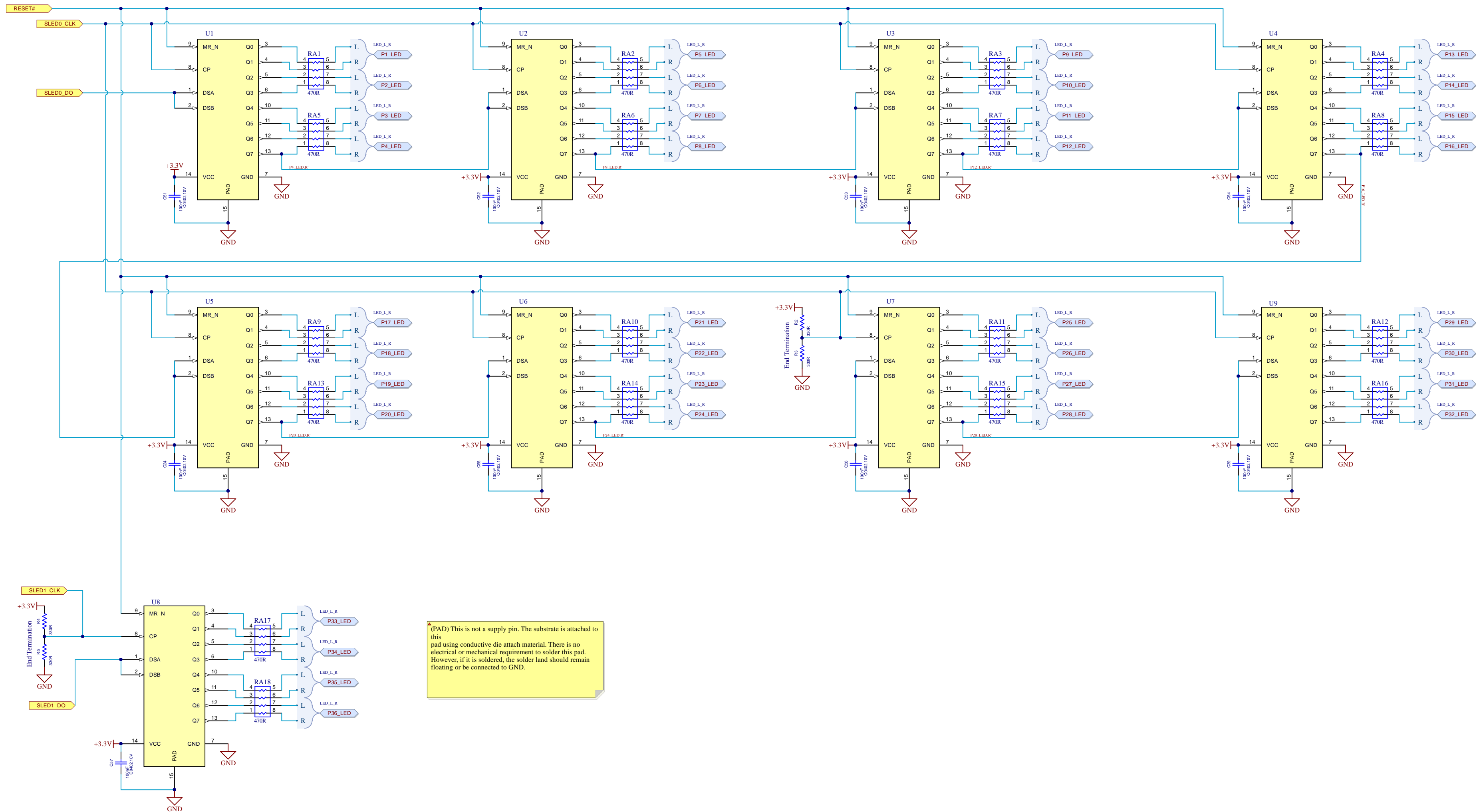












(PAD) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

